



Product Change Notification

Change Notification #: 116283 - 00
Change Title: All Intel® Tray Packed Products,
PCN 116283-00, Transport Media,
Converting to a Universal Plastic Shim on all
Tray Shipments
Date of Publication: July 11, 2018

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	November 13, 2018
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Description of Change to the Customer:

Intel is converting from a corrugated cardboard shim to a plastic shim with one thickness (eliminating "thick" and "thin" shims). The shim is black in color and meets JEDEC standard ESD criteria. The JEDEC dimensions will change as follows:

	Length (mm)	Width (mm)	Thickness (mm)
Current:	327	140	6.2 (thick) / 1.7 (thin)
New:	328	140	4.0

This will apply to all Tray media shipments. One shim is placed on top of the tray stack and a second shim is placed on the bottom of the tray stack when packaged for shipping.

AS-IS Corrugated Shim (Thick/Thin)	TO-BE Plastic Shim
 <p>P/N 500046512 (Thick)</p>  <p>P/N 500046513 (Thin)</p>	 <p>P/N 500135518</p>

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Customers will continue to see thick and thin corrugated cardboard shims until the current inventory is depleted. The new plastic shims are environmentally compliant and can be recycled. Customers will see a mixture of shims used while older inventory is depleted.

Products Affected / Intel Ordering Codes:

All Intel ® Tray packed component products are affected.

PCN Revision History:

Date of Revision:

June 11, 2018

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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